

# Sangsun Yang

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/6789310/publications.pdf>

Version: 2024-02-01

9  
papers

103  
citations

1478505

6  
h-index

1588992

8  
g-index

9  
all docs

9  
docs citations

9  
times ranked

79  
citing authors

#	ARTICLE	IF	CITATIONS
1	Microstructure and mechanical properties of carbon-bearing ultrahigh-strength high Co-Ni Steel (AerMet 340) fabricated via laser powder bed fusion. <i>Materialia</i> , 2021, 20, 101244.	2.7	3
2	Thermo-mechanical evolution of ternary Bi-Sn-In solder micropowders and nanoparticles reflowed on a flexible PET substrate. <i>Applied Surface Science</i> , 2017, 415, 28-34.	6.1	14
3	Microstructure and mechanical behavior of low-melting point Bi-Sn-In solder joints. <i>Electronic Materials Letters</i> , 2017, 13, 420-426.	2.2	15
4	Preparation of Property-Controlled Bi-Based Solder Powders by a Ball-Milling Process. <i>Metals</i> , 2016, 6, 74.	2.3	13
5	Employment of roll-offset printing for fabrication of solder bump arrays: Harnessing the rheological properties of lead-free solder pastes using particle size distribution. <i>Microelectronic Engineering</i> , 2016, 164, 128-134.	2.4	13
6	Oxidation resistant effects of Ag <sub>2</sub> S in Sn-Ag-Al solder: A mechanism for higher electrical conductivity and less whisker growth. <i>Corrosion Science</i> , 2016, 105, 25-35.	6.6	19
7	Fabrication of pre-alloyed Al-Li powders with high Li content via thermal dehydrogenation of LiH and rapid solidification process. <i>Materials and Design</i> , 2016, 94, 159-165.	7.0	21
8	Reduced Electrical Resistivity of Ternary Solder Alloy of Tin&ndash;Copper&ndash;Sulfur: An Anti-Oxidative Role of Sulfur in Binary Solder Alloy of Tin&ndash;Copper. <i>Materials Transactions</i> , 2014, 55, 1513-1516.	1.2	2
9	Low Melting Temperature Solder Materials for Use in Flexible Microelectronic Packaging Applications. , 0, , .		3